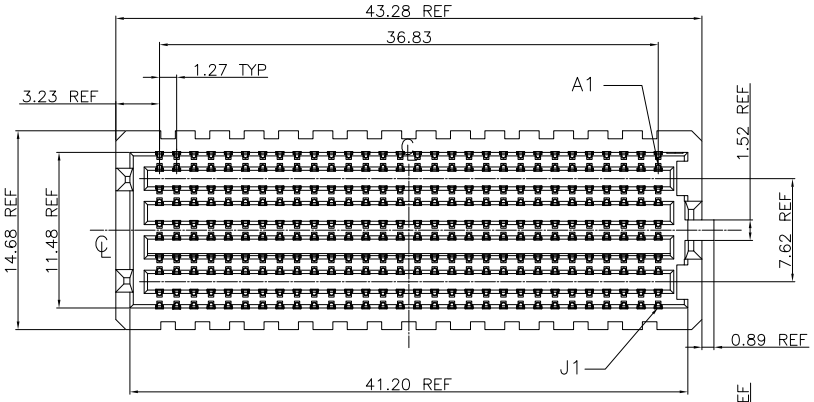
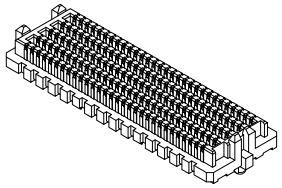
REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN211227	





Material and Plating:

Housing: LCP, UL94V-0 , Black.

Signal Contacts : Phosphor Bronze.

30u"Au+Pd/Ni on Contact Area and 80u" Min Tin Plated on Press Fit over nickel 50u" Min .

Electrical Characteristics:

Current Rating: Signal Pin: 2.7A.

Voltage Rating: 240V AC .

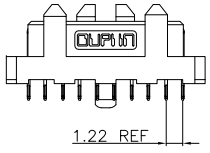
Dielectric Withstanding Voltage: 500V AC For 1 minute.

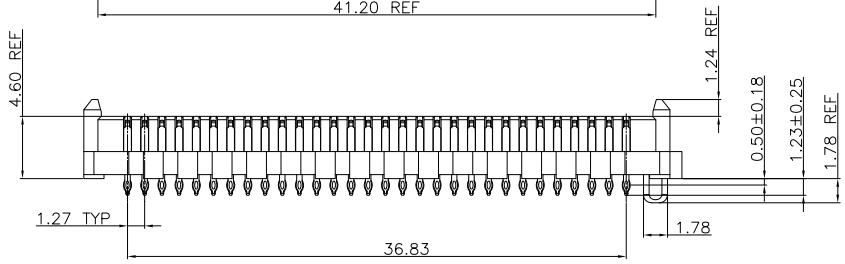
Insulator Resistance: 5000MΩ min at DC 500V.

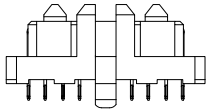
Contact Resistance: Signal: 10mΩ max .

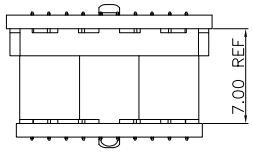
Operating Temperature: -55°C ~ +125°C .

***RoHS Compliant**

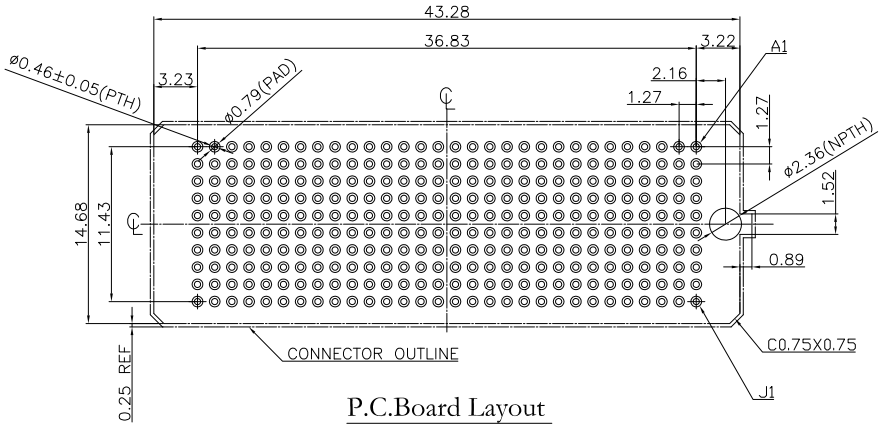








Mating Height



P.C.Board Layout

(Tolerance:±0.05)

2322- 10 X 30 M B 7 P P 1 A

- Series: 2322-
- Row: 10
- Position Per Row: 30
- M: Male
- B: Dip Tin Plated
- Contact Au+Pd/Ni Plated 7: 30μ"
- P: Press Fit Type
- N: W/O Post; P: With Post
- 1:Code 1 height 5.84mm
- A: Tray Package

Tolerances	Dwg. No.	2322-D0000-002	Title: 2322 Series High Speed Board to Board Pitch 1.27mm	OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.			
x = ±0.5	Projection			P/N:	2322-10X30MB7PP1A		
.x = ±0.25	Unit mm	Scale 1:1		SHEET	1/1	Ver. No.	R3
.xx = ±0.15	Drawn By	WP 12/21'21					